Elektronische Bauelemente

SSG16N03-C

16.2A, 30V, $R_{DS(ON)}$ 5.8mΩ
N-Channel Enhancement Mode Power MOSFET

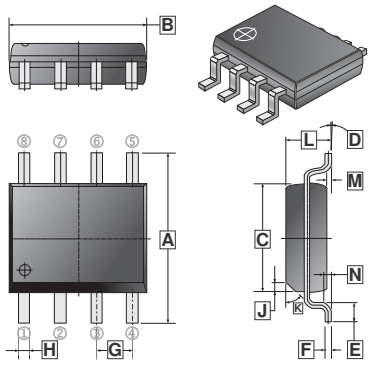
RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

DESCRIPTION

The SSG16N03-C is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications .

The SSG16N03-C meet the RoHS and Green Product requirement with full function reliability approved.

SOP-8

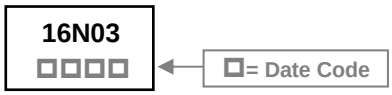


REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.79	6.20	H	0.33	0.51
B	4.70	5.11	J	0.375 REF.	
C	3.80	4.00	K	45°REF.	
D	0°	8°	L	1.3	1.752
E	0.40	1.27	M	0	0.25
F	0.10	0.25	N	0.25 REF.	
G	1.27 TYP.				

FEATURES

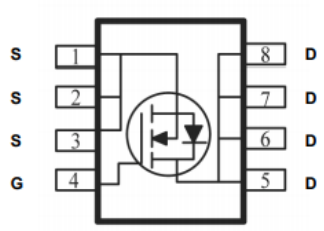
- High Speed Power Switching
- Super Low Gate Charge
- Green Device Available

MARKING



PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8	2.5K	13 inch



ORDER INFORMATION

Part Number	Type
SSG16N03-C	Lead (Pb)-free and Halogen-free

ABSOLUTE MAXIMUM RATINGS (T_A=25℃ unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [1] @V_{GS}=10V	T_A=25℃	I_D	16.2	A
	T_A=70℃		12	
Pulsed Drain Current [2]		I_{DM}	65	A
Single Pulse Avalanche Energy [4]		E_{AS}	80	mJ
Avalanche Current		I_{AS}	40	A
Power Dissipation [3]	T_A=25℃	P_D	3.1	W
Operating Junction & Storage Temperature		T_J, T_{STG}	-55~150	℃
Thermal Resistance Rating				
Thermal Resistance Junction-Ambient [1]		$R_{\theta JA}$	t≦10s, 40	℃/W
			Steady State, 75	
Thermal Resistance Junction-Case [1]		$R_{\theta JC}$	24	

ELECTRICAL CHARACTERISTICS (T_J=25℃ unless otherwise specified)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage		BV_{DSS}	30	-	-	V	V_{GS}=0, I_D= 250μA
Gate-Threshold Voltage		$V_{GS(th)}$	1	-	3	V	V_{DS}=V_{GS}, I_D=250μA
Forward Transfer conductance		g_{fs}	-	43	-	S	V_{DS}=5V, I_D=30A
Gate-Source Leakage Current		I_{GSS}	-	-	±100	nA	V_{GS}= ±20V
Drain-Source Leakage Current	T_J=25℃	I_{DSS}	-	-	1	μA	V_{DS}=24V, V_{GS}=0
	T_J=55℃		-	-	5		
Static Drain-Source On-Resistance [2]		$R_{DS(ON)}$	-	4.3	5.8	mΩ	V_{GS}=10V, I_D=12A
			-	5.6	8		V_{GS}=4.5V, I_D=10A
Gate Resistance		R_g	-	2	-	Ω	f=1MHz
Total Gate Charge		Q_g	-	20	-	nC	I_D=15A V_{DS}=15V V_{GS}=4.5V
Gate-Source Charge		Q_{gs}	-	7.6	-		
Gate-Drain (“Miller”) Change		Q_{gd}	-	7.2	-		
Turn-on Delay Time [2]		$T_{d(on)}$	-	7.8	-	nS	V_{DD}=15V I_D=15A V_{GS}=10V R_G=3.3Ω
Rise Time		T_r	-	15	-		
Turn-off Delay Time		$T_{d(off)}$	-	37.3	-		
Fall Time		T_f	-	10.6	-		
Input Capacitance		C_{iss}	-	2295	-	pF	V_{GS}=0 V_{DS}=15V f=1MHz
Output Capacitance		C_{oss}	-	267	-		
Reverse Transfer Capacitance		C_{rss}	-	210	-		
Guaranteed Avalanche Characteristics							
Single Pulse Avalanche Energy [5]		E_{AS}	28.8	-	-	mJ	V_{DD}=15V, L=0.1mH, I_{AS}=25A
Source-Drain Diode							
Diode Forward Voltage [2]		V_{SD}	-	-	1.2	V	I_S=12A, V_{GS}=0V
Continuous Source Current [1]		I_S	-	-	62	A	V_G=V_D=0, Force Current
Pulsed Source Current [2]		I_{SM}	-	-	150	A	
Reverse Recovery Time		T_{rr}	-	14	-	nS	I_F=30A, dI/dt=100A/μs, T_J=25℃
Reverse Recovery Charge		Q_{rr}	-	5	-	nC	

Notes:

1. The data tested by surface mounted on a 1 inch^2 FR-4 board with 2oz copper.
2. The data tested by pulsed, pulse width≦300μs, duty cycle≦2%.
3. The power dissipation is limited by 150℃ juncti on temperature
4. The E_{AS} data shows Max. rating, The test condition is V_{DD}=15V, V_{GS}=10V, L=0.1mH, I_{AS}=40A.
5. The Min. value is 100% E_{AS} tested guarantee.

CHARACTERISTIC CURVES

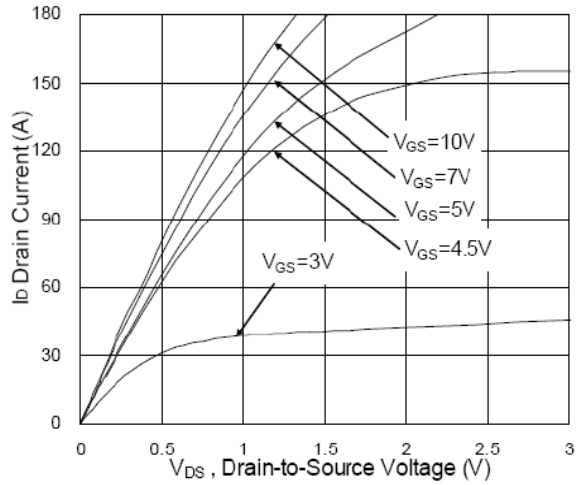


Fig.1 Typical Output Characteristics

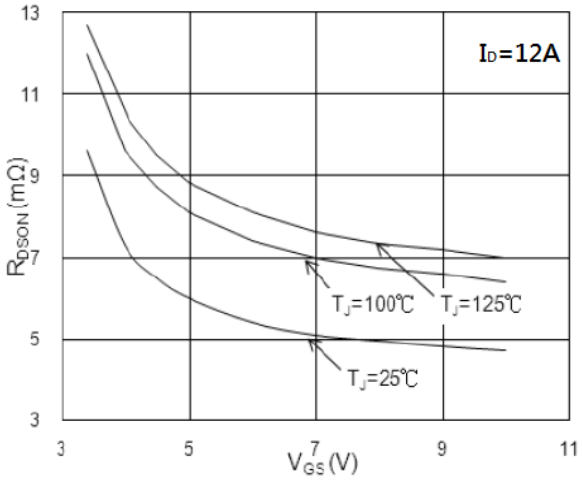


Fig.2 On-Resistance vs. G-S Voltage

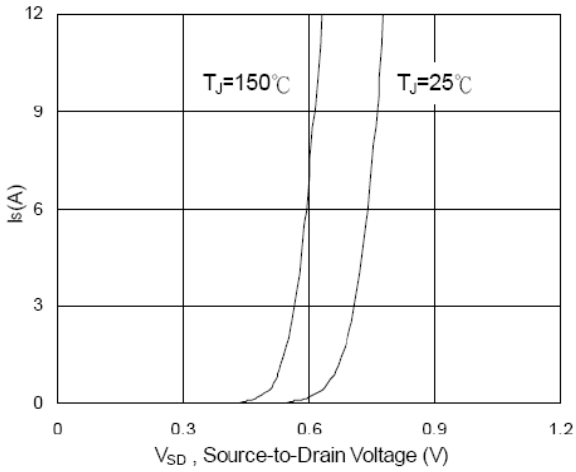


Fig.3 Forward Characteristics of Reverse

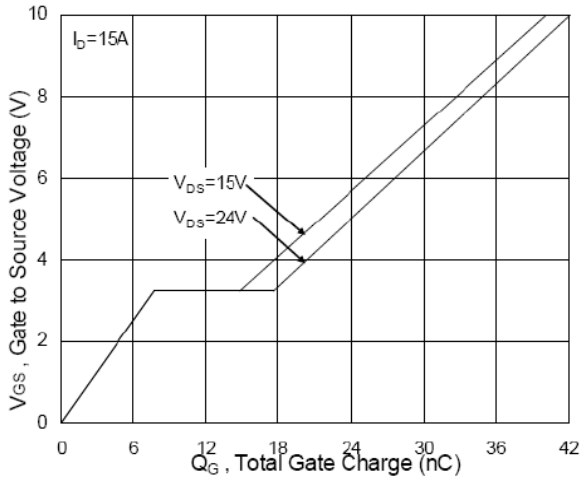


Fig.4 Gate-Charge Characteristics

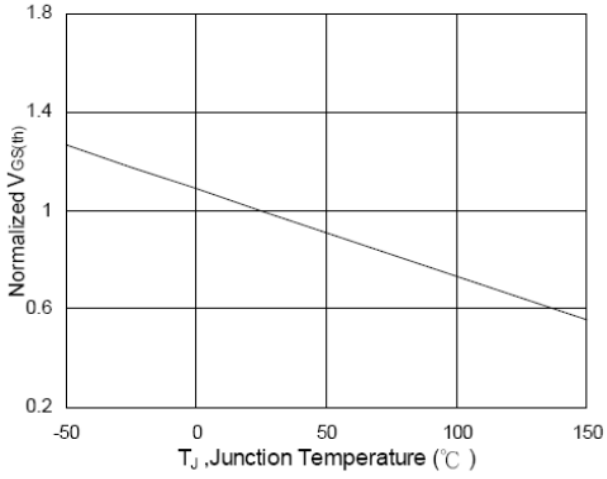


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

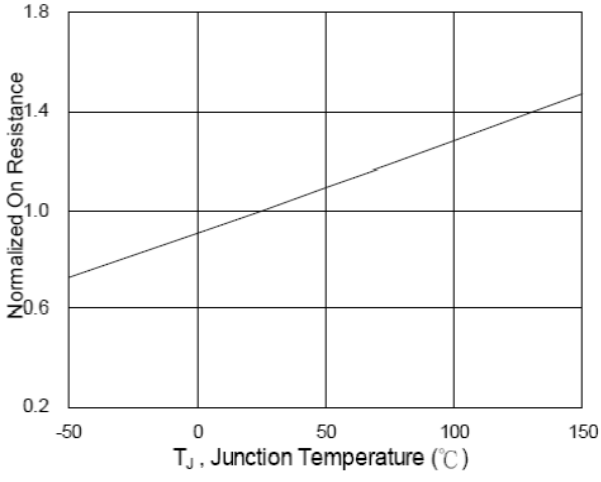


Fig.6 Normalized R_{DSON} vs. T_J

CHARACTERISTIC CURVES

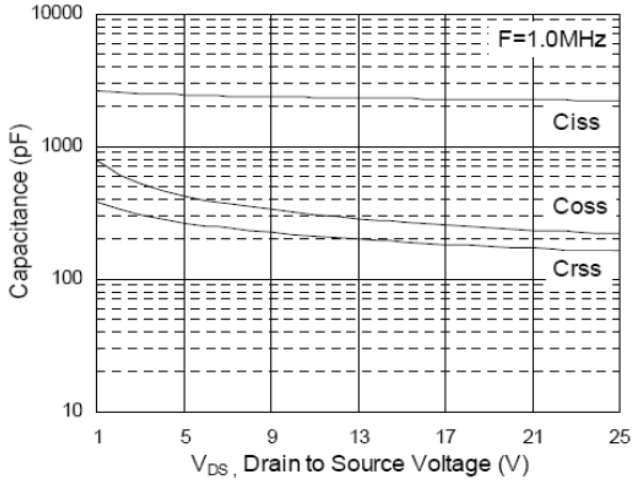


Fig.7 Capacitance

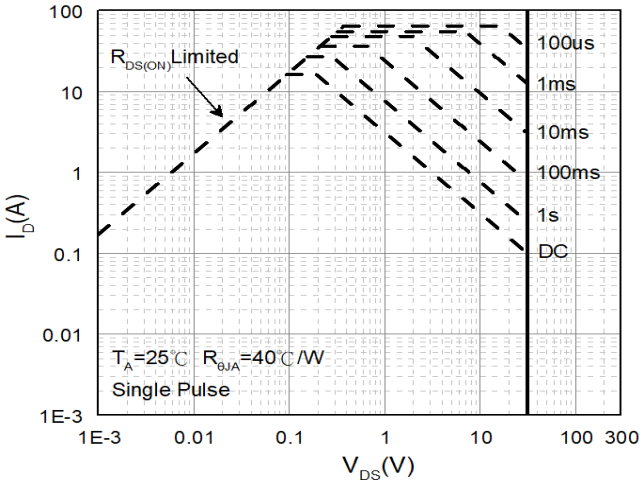


Fig.8 Safe Operating Area

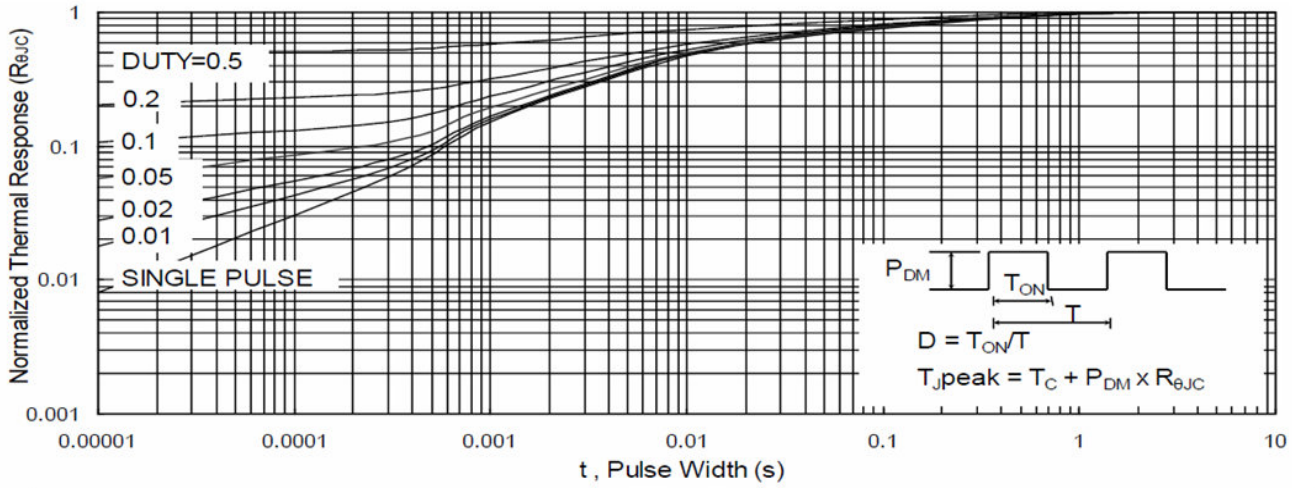


Fig.9 Normalized Maximum Transient Thermal Impedance

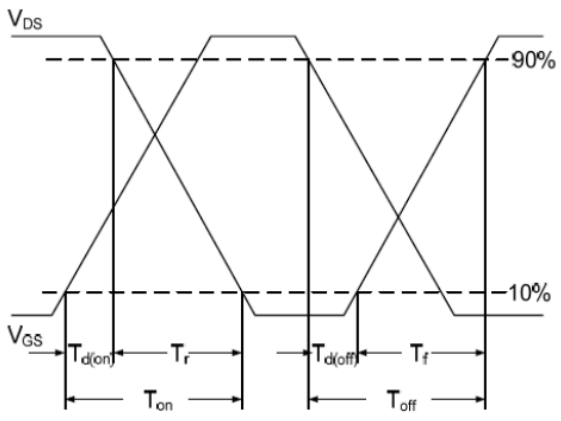


Fig.10 Switching Time Waveform

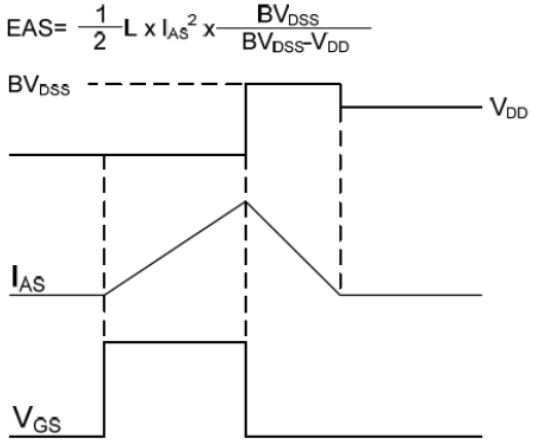
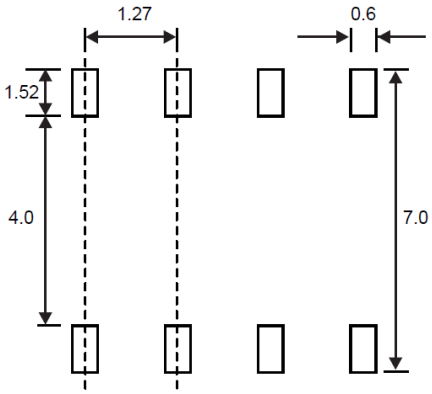


Fig.11 Unclamped Inductive Switching Waveform

CHARACTERISTIC CURVES



*Dimensions in millimeters

Fig.12 Mounting Pad Layout